## ABSTRACT OF THE DISCLOSURE

A digital image capturing module assembly and method of fabricating the same is proposed, which is used for the assembly of a digital image capturing module from a photosensitive printed circuit board and a lens holder. The proposed assembly method is characterized by the provision of stair-like bulged portions beside the aligning posts on the lens holder to allow the formation of an undergap between the photosensitive printed circuit board and the lens holder, which allows a curable and flowable adhesive agent to self-infiltrate into and substantially fill up the undergap through capillary attraction to provide an absolutely sealed light impenetrable effect without the formation of light-penetrating holes around the aligning posts. This feature also allows the overall assembly process to be more simplified, which can help increase the yield of the fabrication of digital image capturing modules.

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